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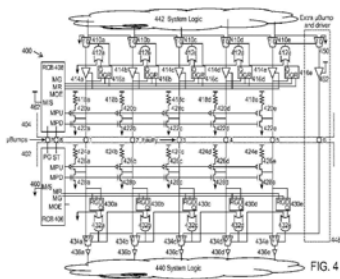
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(57) Abstract :

An apparatus for interconnecting a first die (402) and a second die (404) of a multi die device (400) includes a master circuit block (406) that interfaces with the first die of the multi die device a slave circuit block (408) that interfaces with the second die of the multi die device a first memory (416a 416e) in the slave circuit block a second memory (430a 430e) in the master circuit block and a plurality of μ bumps (1 6) between the first die and the second die wherein the master circuit block and the slave circuit block are configured to identify one of the μ bumps (3) as a faulty μ bump and store a first value that corresponds with the identified faulty μ bump in the first memory.



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